multicomp PRO

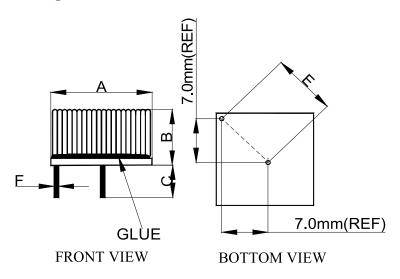




Material List

No.	Item	Material Description
1	Core	T60-75-TAF200 (Red / White)
2	Wire	Ø0.5 mm UEFN/U (155°C)
3	Solder (Lead-free)	Sn99.3% / Cu0.7%
4	Space	FR4 (thickness 1.5mm)
5	Glue	TH320

Configurations and Dimensions



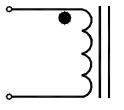
А	18.5mm	(May)	
В	17mm	(Max.)	
С	5.5 ±0.5mm	-	
E	10 ±0.5mm	-	
F Ø0.5mm		(REF.)	

Electrical Characteristics

Test Condition		
10kHz / 0.25 V	L	560μH ±20%
T _A = 25°C	DCR	0.35Ω (Max.)
10kHz / 0.25 V IRMS = 1 A	ΔΤ	Temperature rise 40°C (Max.)

Operating temperature : -55°C to +130°C

Schematic Diagram



Note:

- 1. Wire UEFN/U (155°C) Ø0.5mm
- 2. 76TS (Reference) C.W

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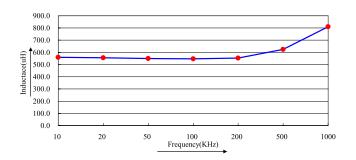
Choke Coil

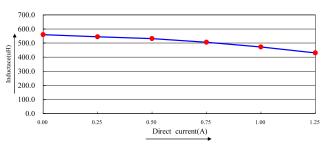


Test Data for Mechanical

Test Item	A (mm)	B (mm)	C (mm)	E (mm)	F (mm)
Specification	18.5 (Max.)	17 (Max.)	5.5 ±0.5	10 ±0.5	Ø0.5 (REF.)
1	17.46	16.38	5.67	9.87	0.49
2	17.43	16.04	5.62	9.94	0.47
3	17.37	16.32	5.63	9.9	0.48
4	17.46	16.21	5.71	10.06	0.49
5	17.73	16.24	5.66	9.95	0.5
Average	17.49	16.24	5.66	9.94	0.49

Electric Characteristics





Test Data for Electrical

Test Item	L µH	DCR Ω	ΔΤ	
Condition	10kHz / 0.25V	T _A = 25°C	10kHz / 0.25V I _{RMS} = 1A	
Specification	560 ±20%	0.35 (Max.)	Temperature rise 40°C (Max.)	
1	558.45			
2	565.25	0.239		
3	571.5		OK	
4	569.05	0.242		
5	565.55	0.239		
Average 565.96		0.24	OK	

Choke Coil



Reliability Test

Test Item	Specifications	Test Method and Remarks	
Operating temperature range	-55°C to +130°C	Including temperature rise due to self-generated heat.	
Storage condition	Ambient temperature : 0°C to 40°C Humidity : Below 70% RH	To maintain the solderability of terminal electrodes, care must be taken to control temperature and humidity in the storage area.	
Moisture sensitivity	Appearance : No abnormality	According to J-STD-020B level 3 Test condition : 60°C 60% RH Test duration : 40hrs Recovery : 1 to 2 hours of recovery under the standard condition after the removal from the test chamber.	
Solderability	All termination shall exhibit a continuous solder coating free from defects for a minimum of 95% of the surface area of any individual lead.	According to J-STD-002B Steam aging category: 97°C 98% RH Steam aging duration: 8 hrs Solder: Lead-free solder Solder temperature: 260 ±5°C Dip time: 5 +0 / -0.5 s	

Part Number Table

Description	Part Number	
Inductor, Toroidal, 560µH, 20%	MCAPB106424076B-561MU	

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